CEL

Solid State Relay
OCMOS FET

PS710CL2-1A

4-PIN DIP, 0.1 Ω LOW ON-STATE RESISTANCE 2.0 A CONTINUOUS LOAD CURRENT 1-ch Optical Coupled MOS FET

–NEPOC Series–

DESCRIPTION

The PS710CL2-1A is a solid state relay containing a GaAs LED on the input side and MOS FETs on the output side.

It is suitable for PLC, etc. because of its large continuous load current and low on-state resistance.

The PS710CL2-1A has a surface mount type with 10.16 mm lead pitch.

FEATURES

- Low on-state resistance (R_{on} = 0.1 Ω TYP.)
- Large continuous load current (I_L = 2.0 A)
- 1 channel type (1 a output)
- Low LED operating current (I_F = 2 mA)
- Designed for AC/DC switching line changer
- Small package (4-pin DIP)
- Low offset voltage
- Ordering number of taping product: PS710CL2-1A-E3, E4: 1 000 pcs/reel

<R>
- Pb-Free product

APPLICATIONS

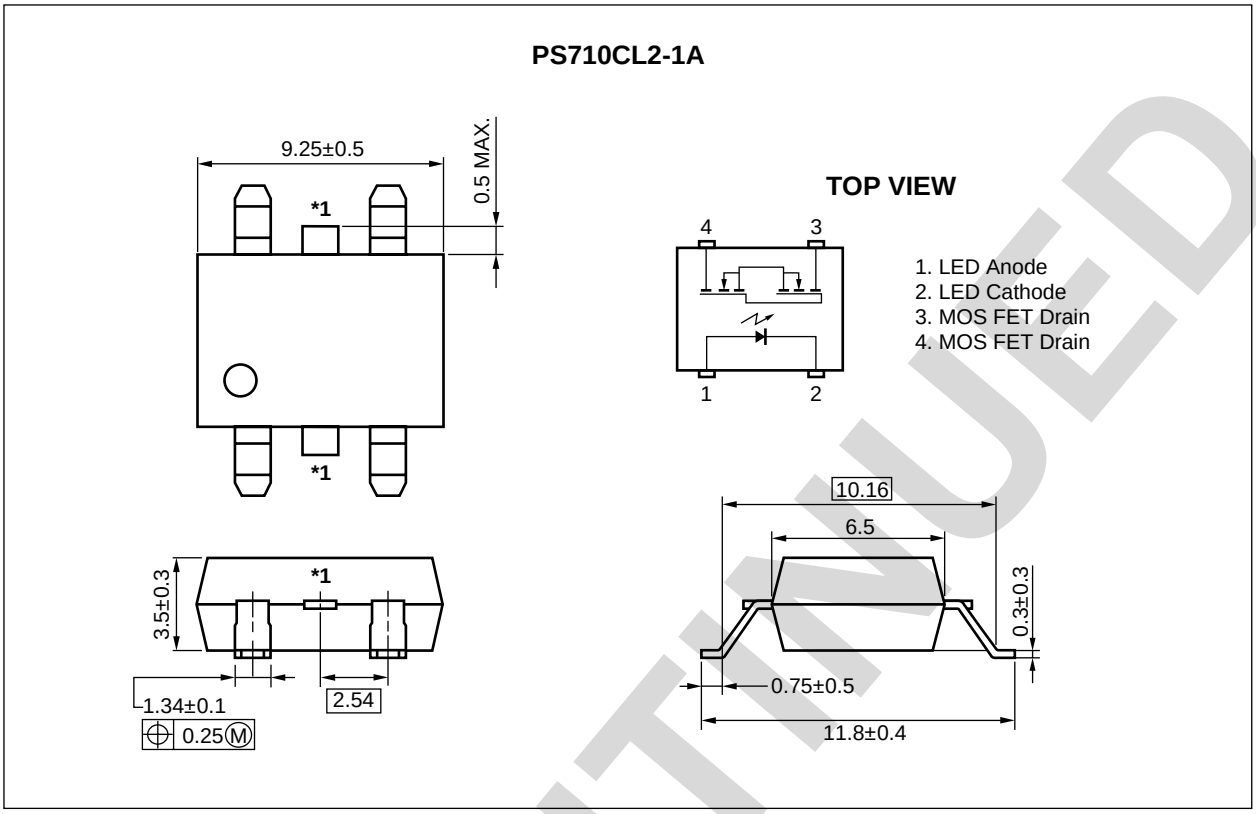
- Measurement equipment
- FA equipment

Document No. PN10164EJ02V0DS (2nd edition)
Date Published July 2006 NS CP(K)

The mark <R> shows major revised points.

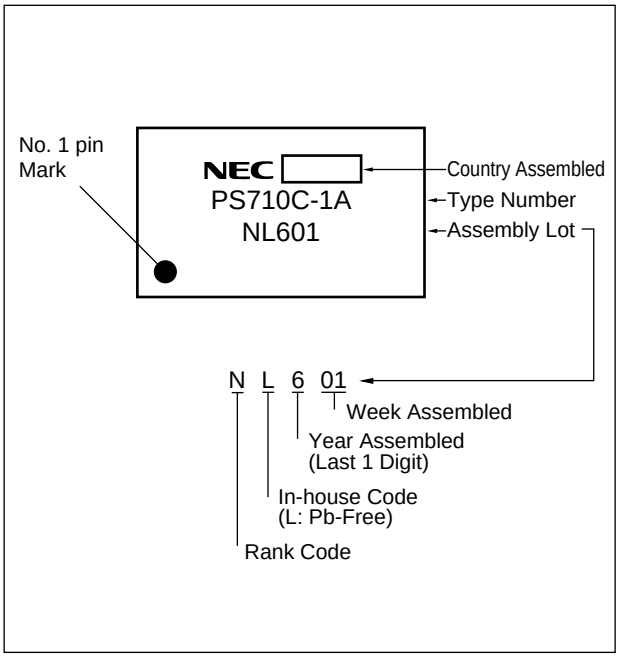
The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (UNIT: mm)



***1** Cut the lead

<R> **MARKING EXAMPLE**



<R> **ORDERING INFORMATION**

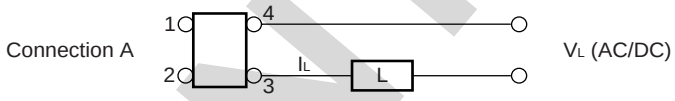
Part Number	Order Number	Solder Plating Specification	Packing Style
PS710CL2-1A	PS710CL2-1A-A	Pb-Free	Magazine case 50 pcs
PS710CL2-1A-E3	PS710CL2-1A-E3-A		Embossed Tape 1 000 pcs/reel
PS710CL2-1A-E4	PS710CL2-1A-E4-A		

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter			Symbol	Ratings	Unit
Diode	Forward Current (DC)		I_F	50	mA
	Reverse Voltage		V_R	5.0	V
	Power Dissipation		P_D	50	mW
	Peak Forward Current *1		I_{FP}	1	A
MOS FET	Load Voltage		V_L	60	V
	Continuous Load Current *2	Connection A	I_L	2.0	A
	Pulse Load Current *3 (AC/DC Connection)		I_{LP}	4.0	A
	Power Dissipation		P_D	600	mW
Isolation Voltage *4			BV	1 500	Vr.m.s.
Total Power Dissipation			P_T	650	mW
Operating Ambient Temperature			T_A	−40 to +85	°C
Storage Temperature			T_{stg}	−40 to +100	°C

***1** PW = 100 μs, Duty Cycle = 1%

***2** Conditions: $I_F \geq 2$ mA. The following types of load connections are available.



***3** PW = 100 ms, 1 shot

***4** AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output
Pins 1-2 shorted together, 3-4 shorted together.

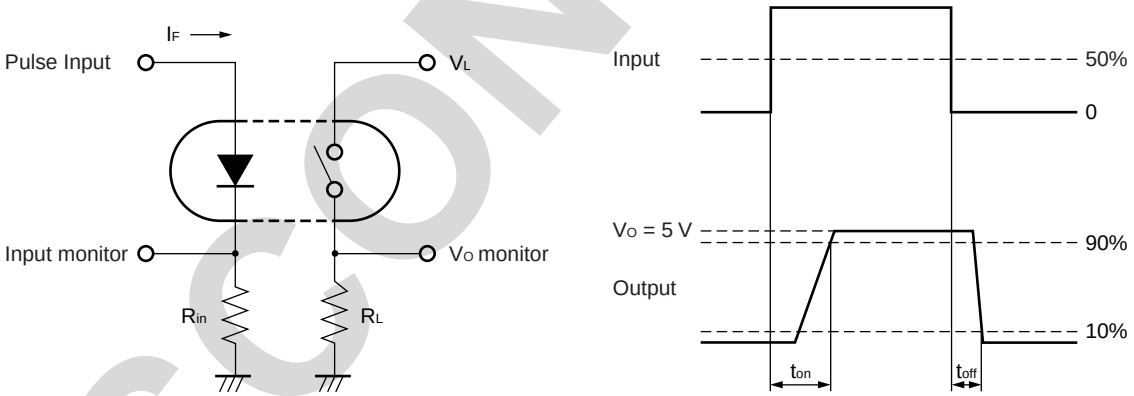
RECOMMENDED OPERATING CONDITIONS (T_A = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I_F	2	10	20	mA
LED Off Voltage	V_F	0		0.5	V

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = 10 mA		1.2	1.4	V
	Reverse Current	I_R	V_R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I_{Loff}	V_D = 60 V			1.0	μA
	Output Capacitance	C_{out}	V_D = 0 V, f = 1 MHz		320		pF
Coupled	LED On-state Current	I_{Fon}	I_L = 2.0 A			2.0	mA
	On-state Resistance	R_{on}	I_F = 10 mA, I_L = 2.0 A, t ≤ 10 ms		0.1	0.15	Ω
	Turn-on Time *1, 2	t_{on}	I_F = 10 mA, V_O = 5 V, R_L = 500 Ω,		1.0	3.0	ms
	Turn-off Time *1, 2	t_{off}	PW ≥ 10 ms		0.05	1.0	
	Isolation Resistance	R_{I-O}	V_{I-O} = 1.0 kV_{DC}	10^9			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1 MHz		0.5		pF

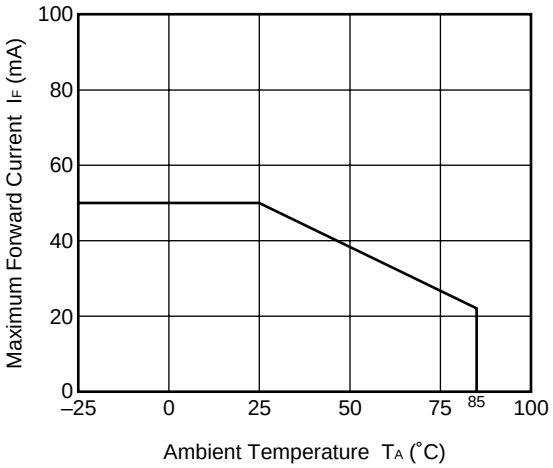
***1** Test Circuit for Switching Time



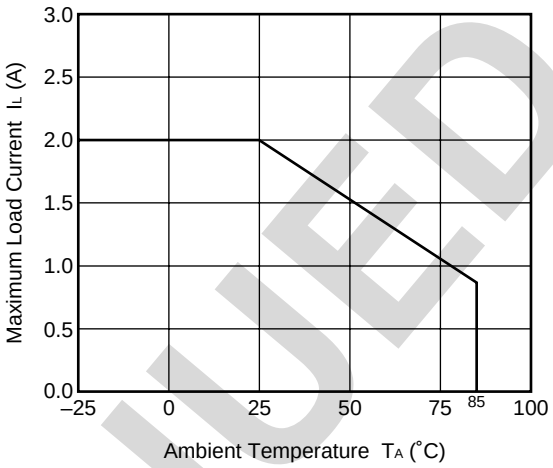
***2** The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)

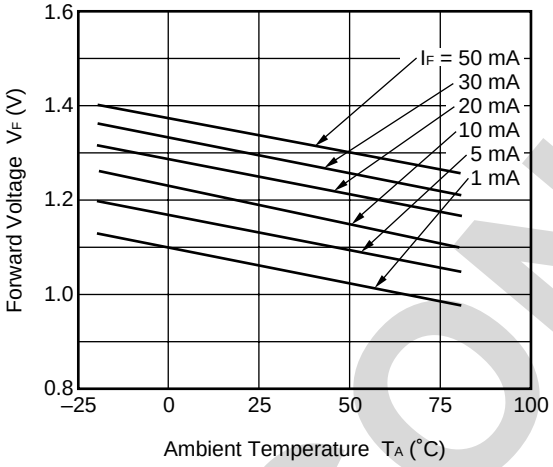
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



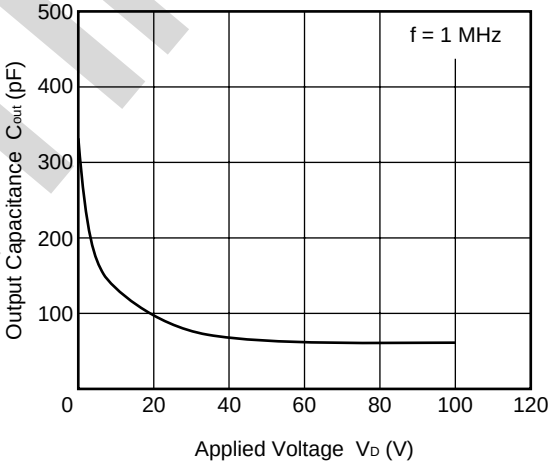
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



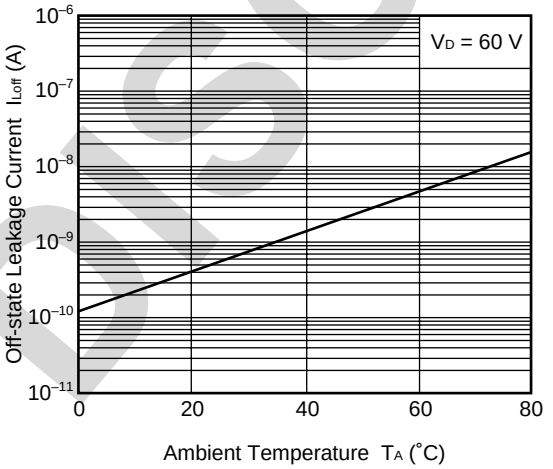
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



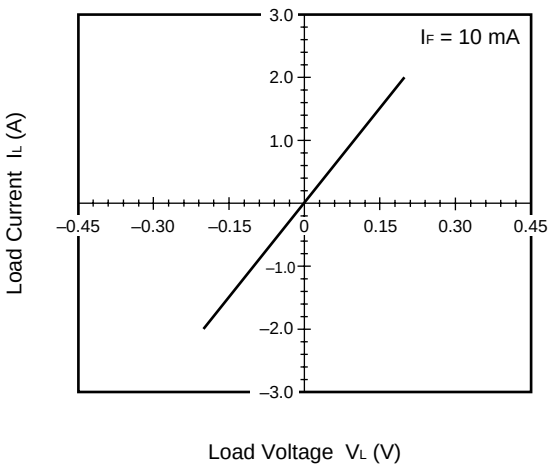
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs. AMBIENT TEMPERATURE

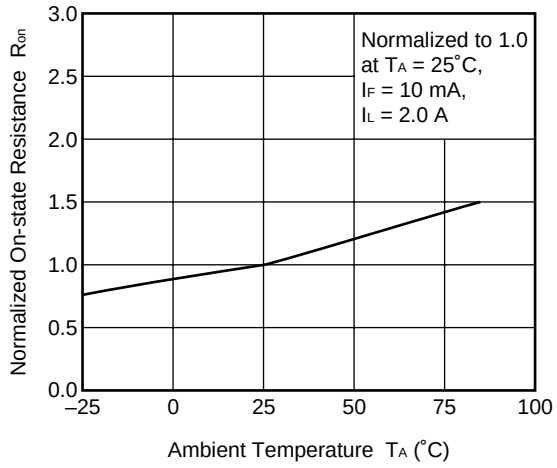


LOAD CURRENT vs. LOAD VOLTAGE

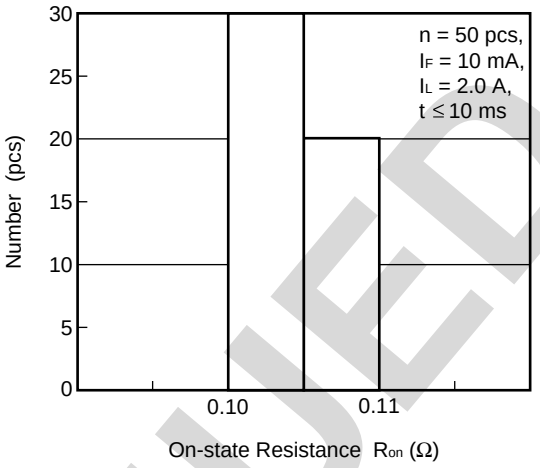


Remark The graphs indicate nominal characteristics.

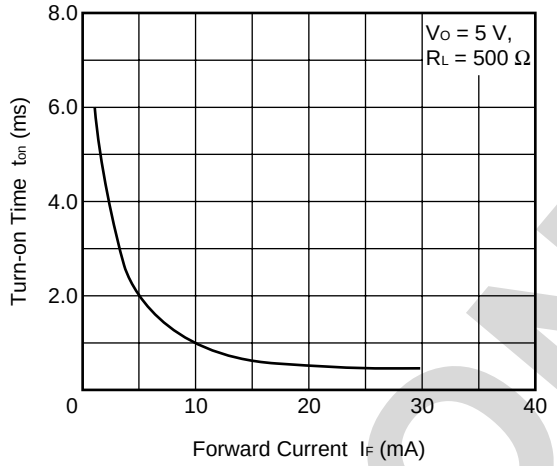
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



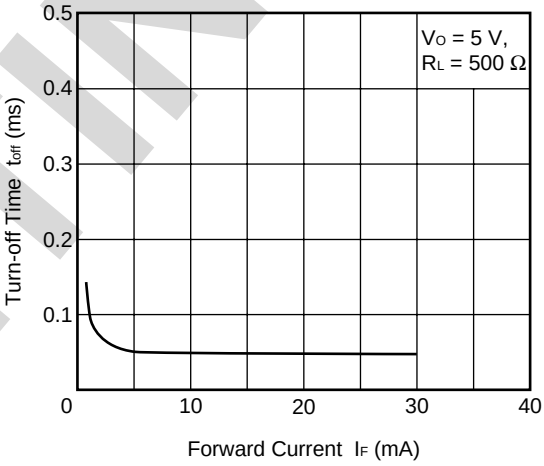
ON-STATE RESISTANCE DISTRIBUTION



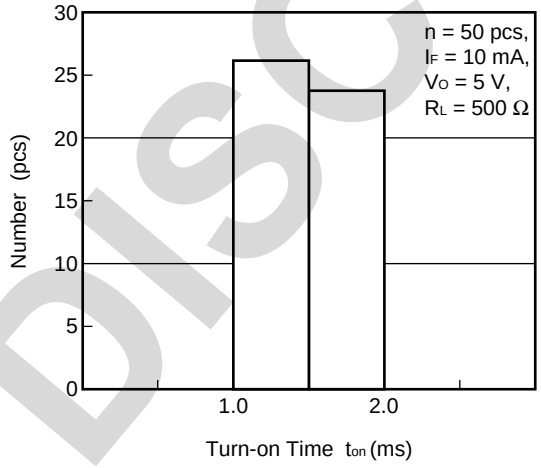
TURN-ON TIME vs. FORWARD CURRENT



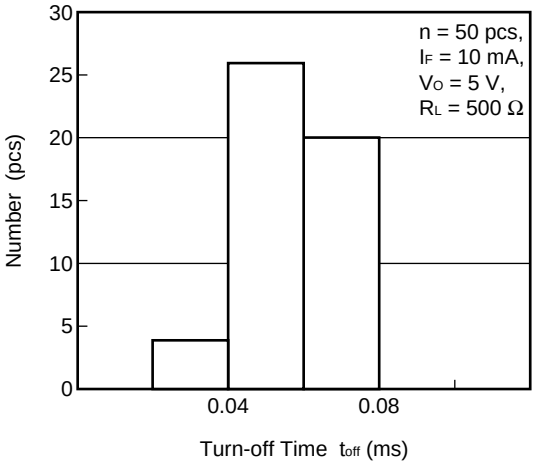
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

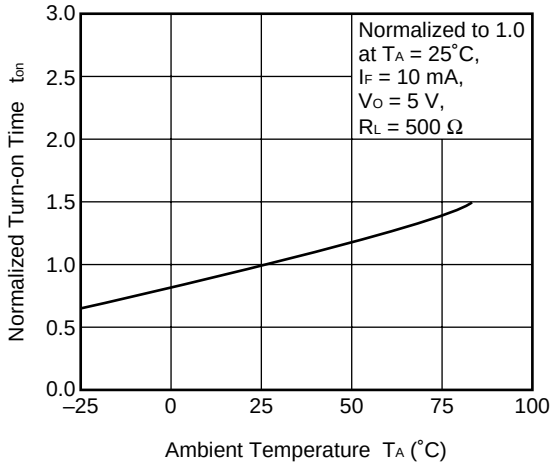


TURN-OFF TIME DISTRIBUTION

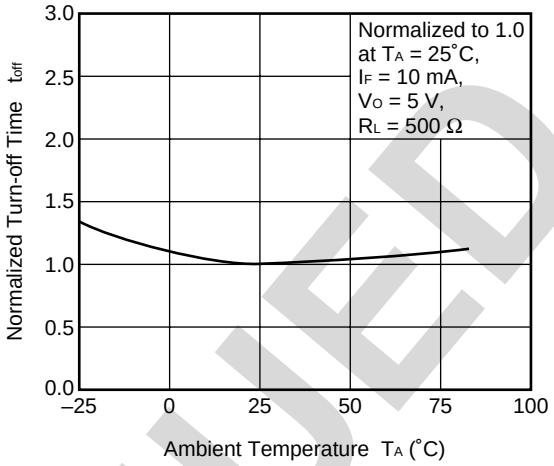


Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



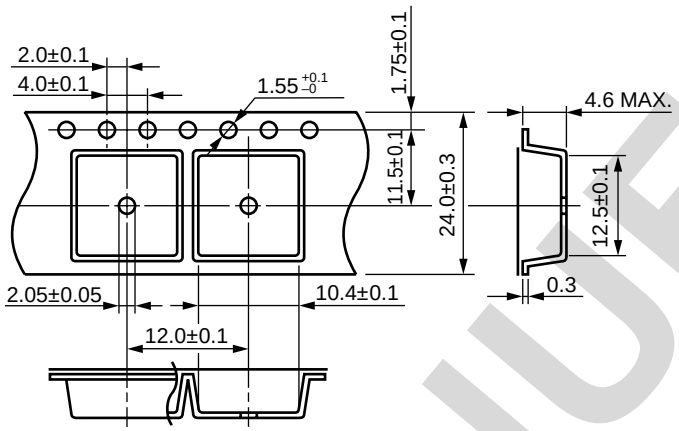
NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



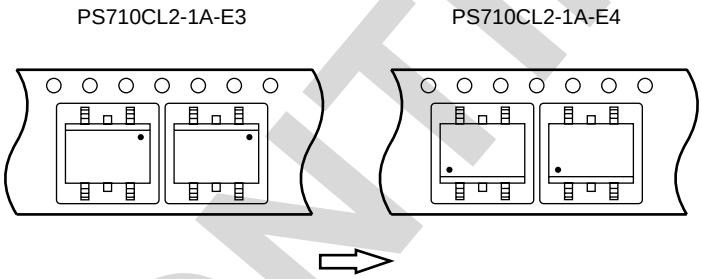
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

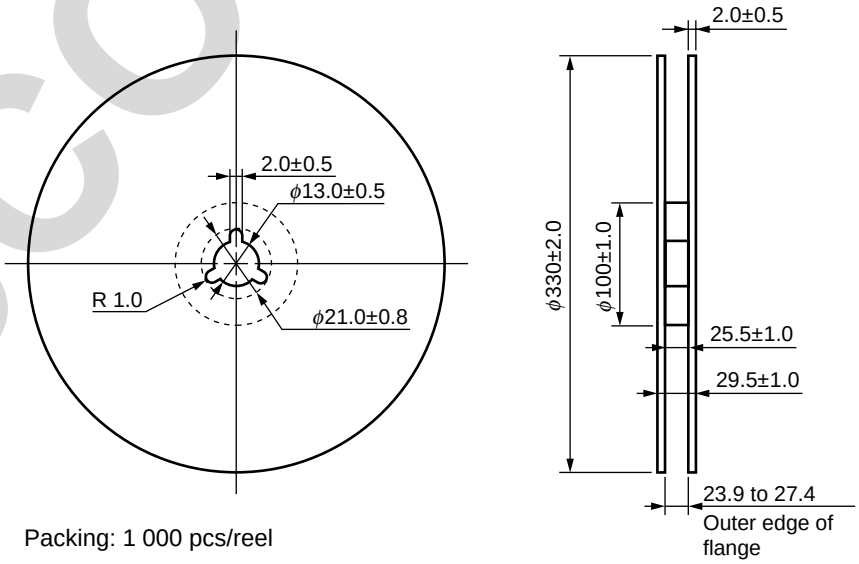
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



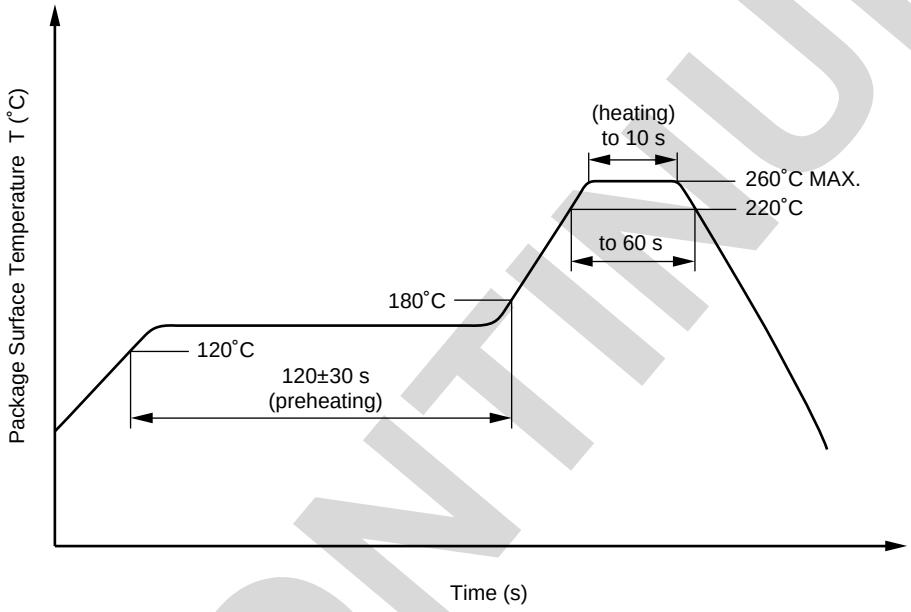
Packing: 1 000 pcs/reel

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

- Peak reflow temperature — 260°C or below (package surface temperature)
- Time of peak reflow temperature — 10 seconds or less
- Time of temperature higher than 220°C — 60 seconds or less
- Time to preheat temperature from 120 to 180°C — 120±30 s
- Number of reflows — Three
- Flux — Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature — 260°C or below (molten solder temperature)
- Time — 10 seconds or less
- Preheating conditions — 120°C or below (package surface temperature)
- Number of times — One
- Flux — Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

<R> **(3) Soldering by soldering iron**

- Peak temperature (lead part temperature) — 350°C or below
- Time (each pins) — 3 seconds or less
- Flux — Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

  Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> **USAGE CAUTIONS**

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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▶**For further information, please contact**

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